AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A process for manufacturing an integrated circuit package comprising:

mounting a semiconductor die to a first surface of a substrate;

mounting a die adapter to said semiconductor die;

wire bonding said semiconductor die to ones of conductive traces of said substrate;

mounting at least one collapsible spacer to at least one of a heat spreader, said die adapter and said substrate;

placing one of said heat spreader and said substrate ~~in a mold cavity~~ on a surface of a lower mold die;

releasably clamping the other of said heat spreader and said substrate to ~~a~~ an upper mold die ~~of said mold cavity~~, such that said collapsible spacer is disposed between said heat spreader and said substrate;

molding ~~a molding compound in the mold, thereby molding~~ the semiconductor die, the substrate, the wire bonds, said die adapter, said at least one collapsible spacer and said heat spreader into ~~the~~ a molding compound by molding in a mold cavity between said other of said heat spreader and said substrate and said surface of the lower mold die, to provide a molded package;

forming a ball grid array on a second surface of said substrate, bumps of said ball grid array being electrically connected to said conductive traces; and

singulating said integrated circuit package.

Claim 2 (currently amended): The process according to claim 1, wherein said

placing one of said heat spreader and said substrate in ~~a~~ the mold cavity comprises placing said heat spreader in said mold cavity such that said heat spreader rests on ~~a lower die of said mold~~ said surface of said lower mold die.

Claim 3 (currently amended): The process according to claim 2, wherein said releasably clamping comprises releasably clamping said substrate to ~~an~~ said upper mold die ~~of said mold~~.

Claim 4 (currently amended): The process according to claim 1, wherein said placing one of said heat spreader and said substrate ~~in a mold cavity~~ on a surface of a lower mold die comprises placing said substrate in said mold cavity such that said substrate rests on ~~a lower die of said mold~~ said surface of said lower mold die.

Claim 5 (currently amended): The process according to claim 4, wherein said releasably clamping comprises releasably clamping said heat spreader to ~~an~~ said upper mold die ~~of said mold~~.

Claim 6 (original): The process according to claim 1, wherein said wire bonding further comprises ground wire bonding said semiconductor die to said die adapter.

Claim 7 (currently amended): The process according to claim 1, wherein said wire bonding further comprises ground wire bonding said semiconductor die to at least one ground pad on said substrate.

Claim 8 (original): The process according to claim 1, wherein said mounting at least one collapsible spacer comprises mounting said at least one collapsible spacer to said substrate.

Claim 9 (original): The process according to claim 1, wherein said mounting at least one collapsible spacer comprises mounting said at least one collapsible spacer to said heat spreader.

Claim 10 (original): The process according to claim 1, wherein said at least one collapsible spacer comprises a plurality of collapsible spacers, and mounting said at least one collapsible spacer comprises mounting one of said plurality of collapsible spacers to said die adapter and mounting at least another of said collapsible spacers to said substrate.

Claim 11 (currently amended): The process according to claim 10, wherein said one of said plurality of collapsible spacers is disposed between said die adapter and said heat spreader and in contact with said die adapter and said heat spreader during molding.

Claim 12 (original): The process according to claim 10, wherein said at least another of said collapsible spacers is disposed in contact with said heat spreader during molding.

Claim 13 (currently amended): A process for manufacturing a plurality of integrated circuit packages comprising:

mounting a plurality of semiconductor dice to a first surface of a substrate array;

mounting a plurality of die adapters to said semiconductor dice such that each one of said die adapters is mounted to a corresponding one of said semiconductor dice;

wire bonding said semiconductor dice to ones of conductive traces of said substrate array;

mounting a collapsible spacer array to one of a heat spreader array and said substrate array;

placing one of said heat spreader array and said substrate array ~~in a mold cavity~~ on a surface of a lower mold die;

releasably clamping the other of said heat spreader array and said substrate array to ~~a first~~ an upper mold die ~~of said mold~~ such that said collapsible spacer array is disposed between said heat spreader array and said substrate array;

molding ~~a molding compound in the mold, thereby molding~~ the semiconductor dice, said substrate array, said wire bonds, said die adapters, said collapsible spacer array and said heat spreader array into ~~the~~ a molding compound by molding in a mold cavity between said other of said heat spreader array and said substrate array and said surface of the lower mold die, to provide an array of molded packages;

forming a plurality of ball grid arrays on a second surface of said substrate array, bumps of said ball grid arrays being electrically connected to said conductive traces; and

singulating each integrated circuit package from said array of molded packages.

Claim 14 (currently amended): The process according to claim 13, wherein said placing one of said heat spreader array and said substrate array ~~in a mold cavity~~ on the surface of the lower mold die comprises placing said heat spreader array in said mold cavity such that said heat spreader array rests on ~~a lower die~~ said surface of said lower mold die ~~of said mold~~.

Claim 15 (currently amended): The process according to claim 14, wherein said releasably clamping comprises releasably clamping said substrate array to ~~an upper die~~ the upper mold die ~~of said mold~~.

Claim 16 (currently amended): The process according to claim 13, wherein said placing one of said heat spreader array and said substrate array ~~in a mold cavity~~ on the surface of the lower mold die comprises placing said substrate array in said mold cavity

such that said substrate array rests on ~~a lower die~~ said surface of said lower mold die ~~of said mold~~.

Claim 17 (currently amended): The process according to claim 16, wherein said releasably clamping, comprises releasably clamping said heat spreader array to ~~an upper die~~ the upper mold die ~~of said mold~~.

Claim 18 (original): The process according to claim 13, wherein said wire bonding further comprises ground wire bonding each of said die adapters to said corresponding one of said semiconductor dice.

Claim 19 (currently amended): The process according to claim 13, wherein said wire bonding further comprises ground wire bonding each of said semiconductor dice to a corresponding ground pad on said substrate array.

Claim 20 (original): The process according to claim 13, wherein said mounting said collapsible spacer array comprises mounting said collapsible spacer array to said substrate array.

Claim 21 (original): The process according to claim 13, wherein said mounting said collapsible spacer array comprises mounting said collapsible spacer array to said heat spreader array.

Claim 22 (original): The process according to claim 19, wherein mounting said collapsible spacer array further comprises mounting a corresponding collapsible spacer of said collapsible spacer array to each of said plurality of die adapters.

Claim 23 (currently amended): The process according to claim 22, wherein said

collapsible spacer array is disposed between said die adapters and said heat spreader array and in contact with said die adapters and heat spreader array during molding.

Claims 24-29 (canceled).